



ZXTP56020FDBQ

20V DUAL PNP LOW V_{CE(SAT)} TRANSISTOR

Features

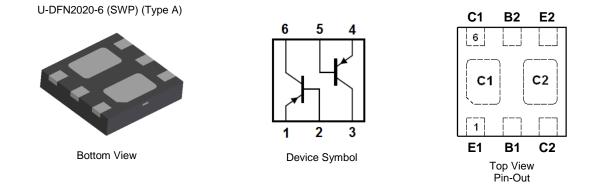
- BV_{CEO} > -20V
- I_C = -2A High Continuous Collector Current
- $R_{CE(SAT)} = 100m\Omega$ for a Low Equivalent On-Resistance
- Low Saturation Voltage V_{CE(SAT)} < -150mV @ -1A
- Sidewall Tin Plating for Wettable Flanks in AOI
- P_D up to 2.47W for Power Demanding Applications
- Low Profile 0.6mm High Package for Thin Applications
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Application

- Matrix LED Lighting
- Power Management

Mechanical Data

- Case: U-DFN2020-6 (SWP) (Type A) with Sidewall Plating (SWP)
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin, Solderable per MIL-STD-202, Method 208 3
- Weight: 0.0065 grams (Approximate)



Ordering Information (Notes 4 & 5)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
ZXTP56020FDBQ-7	1W9	7	8	3,000

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green"

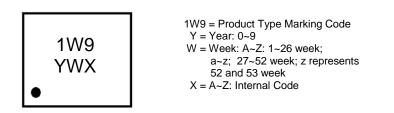
Notes:

and Lead-free. 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product_compliance_definitions.html.

5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information





Absolute Maximum Ratings – Q1 & Q2 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	-20	V
Collector-Emitter Voltage	V _{CEO}	-20	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current	lc	-2	А
Peak Pulse Collector Current	I _{CM}	-3	A
Base Current	Ι _Β	-300	mA
Peak Base Current	I _{BM}	-1	A

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
	(Notes 6 & 8)		405		
Power Dissipation	(Notes 6 & 9)		510	mW	
	(Notes 7 & 8)	PD	1650	TTIVV	
	(Notes 7 & 9)		2470		
	(Notes 6 & 8)		308		
Thermal Desistance Junction to Ambient	(Notes 6 & 9)	5	245	°C/W	
Thermal Resistance, Junction to Ambient	(Notes 7 & 8)	$R_{ heta}$ JA	76	°C/vv	
	(Notes 7 & 9)		51		
Thermal Resistance, Junction to Lead	(Note 10)	$R_{ ext{ heta}JL}$	18	°C/W	
Operating and Storage Temperature Range	_	T _J , T _{STG}	-55 to +150	°C	

ESD Ratings (Note 11)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge – Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge – Machine Model	ESD MM	400	V	С

Notes: 6. For a device mounted with the exposed collector pads on minimum recommended pad layout that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.

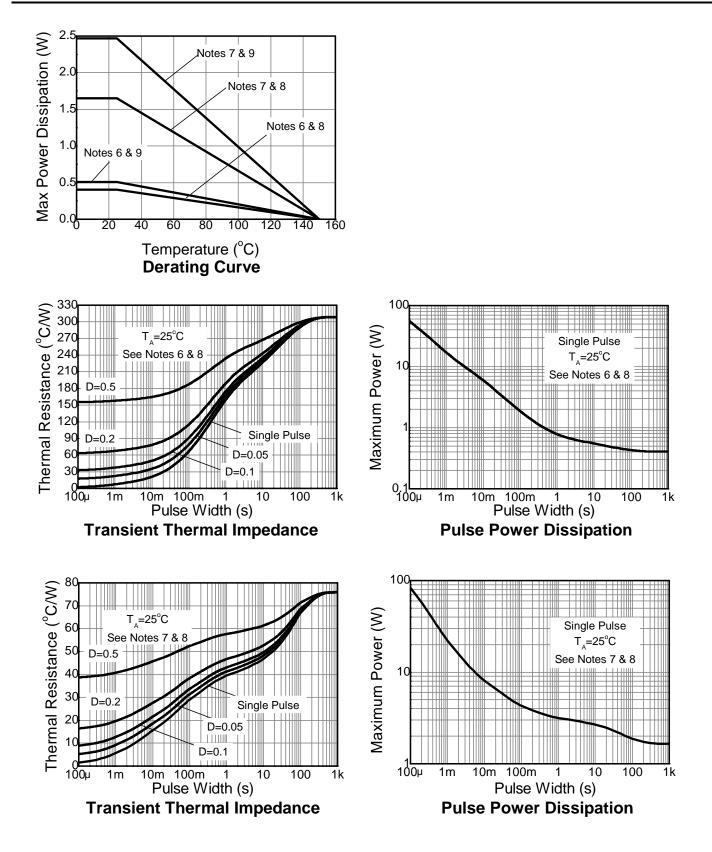
Same as note (6), except the device is mounted with the collector pad on 28mm x 28mm (8cm²) 2oz copper.
For a dual device with one active die.

For dual device with 2 active die running at equal power.
Thermal resistance from junction to solder-point (on the exposed collector pads).
Refer to JEDEC specification JESD22-A114 and JESD22-A115.



ZXTP56020FDBQ

Thermal Characteristics and Derating Information





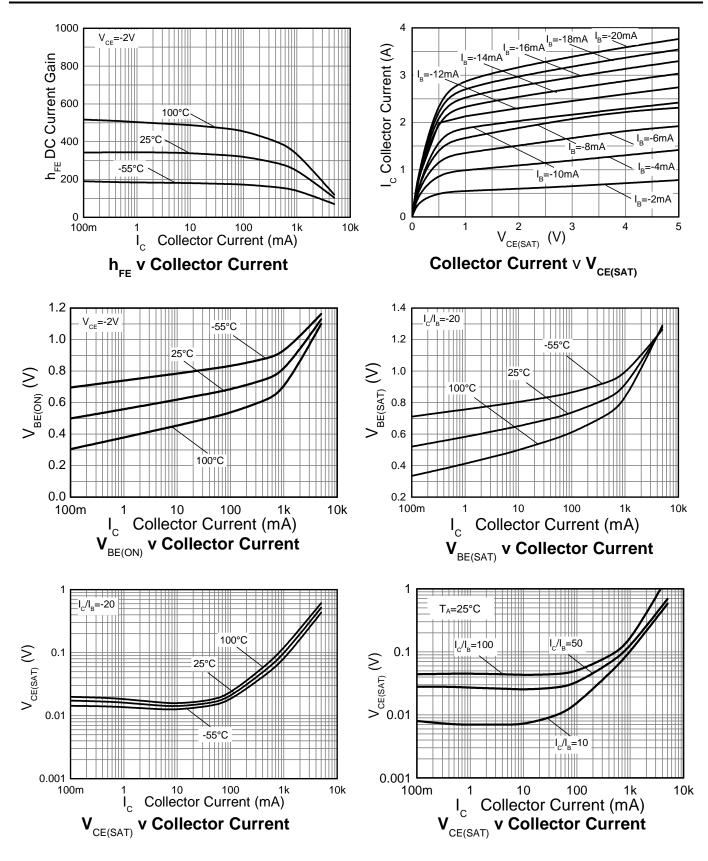
Electrical Characteristics – Q1 & Q2 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Мах	Unit	Test Conditions
		-20	тур	IVIAN	V	
Collector-Base Breakdown Voltage	BV _{CBO}				-	$I_{C} = -100 \mu A$
Collector-Emitter Breakdown Voltage (Note 12)	BV _{CEO}	-20	—	—	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	—	_	V	I _E = -100μA
Collector-Base Cutoff Current	I _{CBO}	_		-100	nA	$V_{CB} = -16V, I_E = 0$
		_		-50	μA	$V_{CB} = -16V, I_E = 0, T_A = +150^{\circ}C$
Emitter-Base Cutoff Current	I _{EBO}	_	_	-100	nA	$V_{EB} = -5.6V, I_{C} = 0$
		250				$V_{CE} = -2V, I_{C} = -100mA$
		210				$V_{CE} = -2V, I_{C} = -500mA$
DC Current Gain (Note 12)	hFE	170				$V_{CE} = -2V, I_{C} = -700mA$
		160				$V_{CE} = -2V, I_{C} = -1A$
		100	—			$V_{CE} = -2V, I_{C} = -2A$
		_	—	-110		$I_{C} = -500 \text{mA}, I_{B} = -50 \text{mA}$
		—		-220	mV	$I_{C} = -1A, I_{B} = -50mA$
Collector-Emitter Saturation Voltage (Note 12)	Vce(sat)	_	—	-200		I _C = -0.7A, I _B = -7mA
		_	_	-390		I _C = -2A, I _B = -200mA
Equivalent On-Resistance (Note 12)	R _{CE(SAT)}			220	mΩ	I _E = -1A, I _B = -50mA
	V _{BE(SAT)}	_	_	-1	V	I _C = -0.5A, I _B = -50mA
Base-Emitter Saturation Voltage (Note 12)		_	_	-1.1		I _C = -1A, I _B = -50mA
		_	_	-1.25		$I_{C} = -2A, I_{B} = -200mA$
Base-Emitter Turn-on Voltage (Note 12)	V _{BE(ON)}			-0.9	V	$V_{CE} = -2V, I_{C} = -0.5A$
Turn-On Time	t _{ON}	_	60	_	ns	
Delay Time	t _D	t _D 10 ns		ns	$I_{C} = -1A, I_{B1} = -I_{B2} = 50mA;$	
Rise Time	t _R	_	50		ns	T _A = +25°C

Note: 12. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.



Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

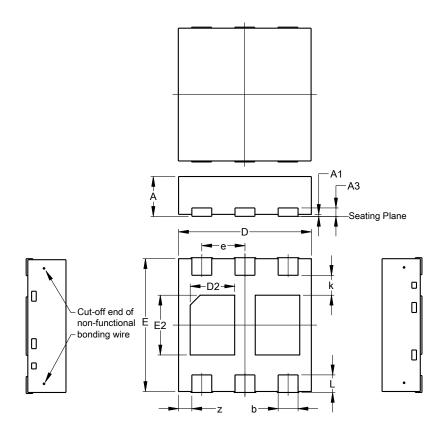




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (SWP) (Type A)

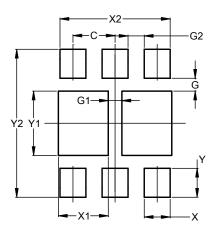


U-DFN2020-6 (SWP)						
	(Type A)					
Dim	Min	Max	Тур			
Α	0.55	0.65	0.60			
A1	0.00	0.05	0.03			
A3			0.127			
b	0.25	0.35	0.30			
D	1.95	2.05	2.00			
D2	0.57	0.77	0.67			
ш	1.95	2.05	2.00			
E2	0.80	1.00	0.90			
e	0.65BSC					
k	0.30BSC					
L	0.22	0.32	0.27			
z	0.20BSC					
All	All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (SWP) (Type A)



Dimensions	Value (in mm)		
С	0.650		
G	0.200		
G1	0.210		
G2	0.250		
Х	0.400		
X1	0.770		
X2	1.700		
Y	0.450		
Y1	1.000		
Y2	2.300		



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